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Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-02-10
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	AYA4*U6BAABU	A	SA1A	2016-02-10
Amount	UoM	Unit type	ST ECOPACK Grade	
2.4	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	1.3x1.6x0.55	6	No lead	
Comment	Package: AOGL UDFN-6L 1.3X1.6 X0.55 PITCH 0.40; MDF valid for SR2UABU			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AYA4*U6BAABU					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.247	mg		Silicon die	Silicon (Si)	7440-21-3		0.242	mg	979757	100833
Die					Passivation	Gamma-butyrolactone	96-48-0		0.003	mg	12146	1250
Die					Passivation	Polyhydroxyamide	55295-98-2		0.002	mg	8097	833
Lead frame	Copper & its alloys	0.668	mg		Alloy	Copper (Cu)	7440-50-8		0.65	mg	973054	270833
Lead frame					Alloy	Silicon (Si)	7440-21-3		0.003	mg	4491	1250
Lead frame					Alloy	Iron (Fe)	7439-89-6		0.001	mg	1497	417
Lead frame					Alloy	Magnesium (Mg)	7439-95-4		0.001	mg	1497	417
Lead frame					Alloy	Zinc (Zn)	7440-66-6		0.003	mg	4491	1250
Lead frame					Alloy	Manganese (Mn)	7439-96-5		0.003	mg	4491	1250
Lead frame	Nickel (Ni)				Coating	Nickel (Ni)	7440-02-0		0.005	mg	7485	2083
Lead frame	Precious metals				Coating	Palladium (Pd)	7440-05-3		0.001	mg	1497	417
Lead frame	Precious metals				Coating	Gold (Au)	7440-57-5		0.001	mg	1497	417
Die attach	Other Organic Materials	0.043	mg		Glue	Aluminium oxide	1344-28-1		0.013	mg	302326	5417
Die attach					Glue	Diethylene glycol monoethyl ether acetate	112-15-2		0.017	mg	395349	7083
Die attach					Glue	Epoxy resin(1-10%)	25068-38-6		0.003	mg	69767	1250
Die attach					Glue	Epoxy resin (10-30%)	Proprietary		0.008	mg	186047	3333
Die attach					Glue	Aromatic amine	Proprietary		0.002	mg	46512	833
Bonding wire	Precious metals	0.025	mg		Bonding wire	Gold (Au)	7440-57-5		0.025	mg	1000000	10417
Encapsulation	Other Organic Materials	1.418	mg		Molding compound	Silica fused	60676-86-0		1.328	mg	936530	553333
Encapsulation					Molding compound	Epoxy resin	Proprietary		0.043	mg	30324	17917
Encapsulation					Molding compound	Phenol resin	Proprietary		0.043	mg	30324	17917
Encapsulation					Molding compound	Carbon black	1333-86-4		0.004	mg	2821	1667